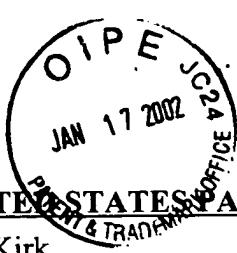


S/N 09/945,394



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

RECEIVED

Applicant: Steve Van Kirk

Examiner:

FEB -4 2002

Serial No.: 09/945,394

Group Art Unit: 2836

TECHNOLOGY CENTER;

Filed: August 30, 2001

Docket: 303.755US1

Title: CIRCUIT BOARD PLANE INTERLEAVE APPARATUS AND METHOD

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Before taking up the above-identified application for examination, please enter the following amendments.

IN THE SPECIFICATION

Please make the paragraph substitutions indicated in the appendix entitled Clean Version of Amended Specification Paragraphs. The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs:

The paragraph beginning on page 10, line 5, is amended as follows:

Several parameters of the physical interface between the interstices 150,160, or tongue/grooves 112/124, 122/114 can also be adjusted. Again, these variations serve most directly to affect the value of capacitance measured between the conductive layers 110, 120, i.e., for the capacitor 95. For example, the separation distance "R" between the tongues 112, [114] 122 can be adjusted. This type of adjustment will inherently affect the spacing "U" between the upper-inner wall of the interstice 160 and the outer wall of the tongue 112, as well as the spacing "L" between the lower-inner wall of the interstice 150 and the outer edge of the tongue [114] 122. However, if such additional changes are undesired, then the thickness T1, T2 of the tongues 112, [114] 122 may also be adjusted to compensate for the relative movement brought about by varying the separation distance "R".

The paragraph beginning on page 14, line 3 is amended as follows:

As mentioned previously, there is no ultimate limit, other than practicality (e.g. overall cost, manufacturing processes complexity, time required, etc.), to the number of interstices, or the shape of the interstices or tongues/grooves, used for engagement between the conductive layer 110 and the conductive layer 120. For example, as can be seen in Figure 9, a plurality of